

Memory FRAM

4 M Bit (512 K × 8)

MB85R4001A

■ DESCRIPTIONS

The MB85R4001A is an FRAM (Ferroelectric Random Access Memory) chip consisting of 524,288 words × 8 bits of nonvolatile memory cells fabricated using ferroelectric process and silicon gate CMOS process technologies.

The MB85R4001A is able to retain data without using a back-up battery, as is needed for SRAM.

The memory cells used in the MB85R4001A can be used for 10^{10} read/write operations, which is a significant improvement over the number of read and write operations supported by Flash memory and E²PROM.

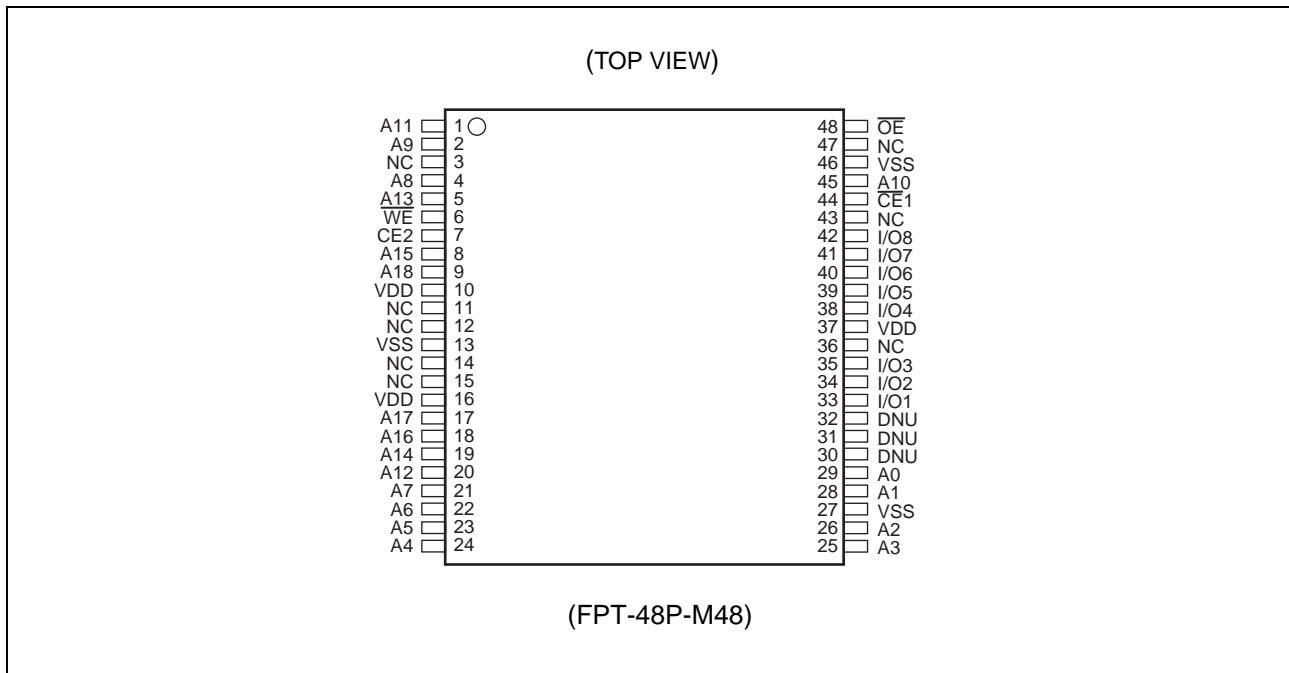
The MB85R4001A uses a pseudo-SRAM interface that is compatible with conventional asynchronous SRAM.

■ FEATURES

- Bit configuration : 524,288 words × 8 bits
- Read/write endurance : 10^{10} times / byte
- Data retention : 10 years (+ 55 °C), 55 years (+ 35 °C)
- Operating power supply voltage : 3.0 V to 3.6 V
- Low power operation : Operating power supply current 15 mA (Typ)
Standby current 50 μA (Typ)
- Operation ambient temperature range : - 40 °C to + 85 °C
- Package : 48-pin plastic TSOP (FPT-48P-M48)
RoHS compliant

MB85R4001A

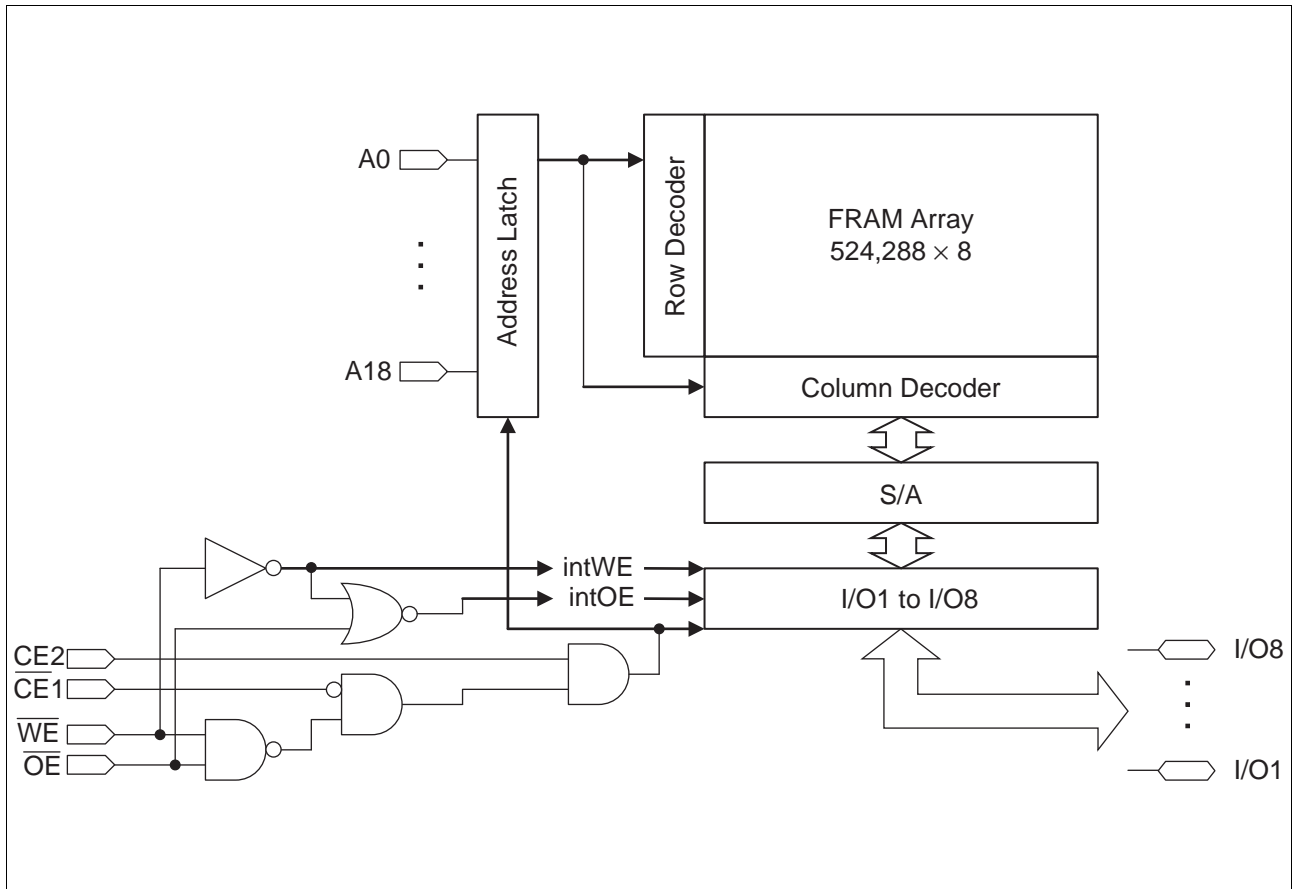
■ PIN ASSIGNMENTS



■ PIN DESCRIPTIONS

Pin Number	Pin Name	Functional Description
1, 2, 4, 5, 8, 9, 17 to 26, 28, 29, 45	A0 to A18	Address Input pins
33 to 35, 38 to 42	I/O1 to I/O8	Data Input/Output pins
44	$\overline{CE}1$	Chip Enable 1 Input pin
7	CE2	Chip Enable 2 Input pin
6	\overline{WE}	Write Enable Input pin
48	\overline{OE}	Output Enable Input pin
10, 16, 37	VDD	Supply Voltage pins Connect all three pins to the power supply.
13, 27, 46	VSS	Ground pins Connect all three pins to ground.
3, 11, 12, 14, 15, 36, 43, 47	NC	No Connect pins Leave these pins open, or connect to VDD or VSS.
30 to 32	DNU	Do Not Use pins Make sure to connect these pins to ground.

■ BLOCK DIAGRAM



■ FUNCTIONAL TRUTH TABLE

Operation Mode	$\overline{CE1}$	$CE2$	\overline{WE}	\overline{OE}	I/O ₁ to I/O ₈	Supply Current
Standby Precharge	H	X	X	X	Hi-Z	Standby (I _{SB})
	X	L	X	X		
	X	X	H	H		
Read	\downarrow	H	H	L	Data Output	Operation (I _{DD})
	L	\uparrow				
Read (Pseudo-SRAM, \overline{OE} control*1)	L	H	H	\downarrow		
Write	\downarrow	H	L	H	Data Input	
	L	\uparrow				
Write (Pseudo-SRAM, \overline{WE} control*2)	L	H	\downarrow	H		

Note: L = V_{IL}, H = V_{IH}, X can be either V_{IL}, V_{IH}, \downarrow or \uparrow , Hi-Z = High Impedance

\downarrow : Latch address and latch data at falling edge, \uparrow : Latch address and latch data at rising edge

*1 : \overline{OE} control of the Pseudo-SRAM means the valid address at the falling edge of \overline{OE} to read.

*2 : \overline{WE} control of the Pseudo-SRAM means the valid address and data at the falling edge of \overline{WE} to write.

MB85R4001A

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating		Unit
		Min	Max	
Power Supply Voltage*	V_{DD}	- 0.5	+ 4.0	V
Input Pin Voltage*	V_{IN}	- 0.5	$V_{DD} + 0.5 (\leq 4.0)$	V
Output Pin Voltage*	V_{OUT}	- 0.5	$V_{DD} + 0.5 (\leq 4.0)$	V
Operation Ambient Temperature	T_A	- 40	+ 85	°C
Storage Temperature	T_{STG}	- 55	+ 125	°C

* : All voltages are referenced to VSS (ground 0 V).

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value			Unit
		Min	Typ	Max	
Power Supply Voltage*	V_{DD}	3.0	3.3	3.6	V
High Level Input Voltage*	V_{IH}	$V_{DD} \times 0.8$	—	$V_{DD} + 0.5 (\leq 4.0)$	V
Low Level Input Voltage*	V_{IL}	- 0.5	—	+ 0.6	V
Operation Ambient Temperature	T_A	- 40	—	+ 85	°C

* : All voltages are referenced to VSS (ground 0 V).

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

1. DC Characteristics

(within recommended operating conditions)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Input Leakage Current*1	$ I_{LI} $	$V_{IN} = 0 \text{ V to } V_{DD}$	—	—	10	μA
Output Leakage Current	$ I_{LO} $	$V_{OUT} = 0 \text{ V to } V_{DD}$, $\overline{CE1} = V_{IH}$ or $\overline{OE} = V_{IH}$	—	—	10	μA
Operating Power Supply Current*2	I_{DD}	$\overline{CE1} = 0.2 \text{ V}$, $\overline{CE2} = V_{DD}-0.2 \text{ V}$, $I_{out} = 0 \text{ mA}$	—	15	20	mA
Standby Current*3	I_{SB}	$\overline{CE1} \geq V_{DD}-0.2 \text{ V}$	—	50	150	μA
		$\overline{CE2} \leq 0.2 \text{ V}$				
		$\overline{OE} \geq V_{DD}-0.2 \text{ V}$, $\overline{WE} \geq V_{DD}-0.2 \text{ V}$				
High Level Output Voltage	V_{OH}	$I_{OH} = -1.0 \text{ mA}$	$V_{DD} \times 0.8$	—	—	V
Low Level Output Voltage	V_{OL}	$I_{OL} = 2.0 \text{ mA}$	—	—	0.4	V

*1 : This also applies to DNU pins.

*2 : During the measurement of I_{DD} , the Address and Data In were taken to only change once per active cycle.
 I_{out} : output current

*3 : All pins other than setting pins shall be input at the CMOS level voltages such as $H \geq V_{DD} - 0.2 \text{ V}$, $L \leq 0.2 \text{ V}$.

2. AC Characteristics

• AC Test Conditions

Power Supply Voltage	: 3.0 V to 3.6 V
Operation Ambient Temperature	: -40 °C to +85 °C
Input Voltage Amplitude	: 0.3 V to 2.7 V
Input Rising Time	: 5 ns
Input Falling Time	: 5 ns
Input Evaluation Level	: 2.0 V / 0.8 V
Output Evaluation Level	: 2.0 V / 0.8 V
Output Load Capacitance	: 50 pF

(1) Read Cycle

Parameter	Symbol	Value		Unit
		Min	Max	
Read Cycle Time	t _{RC}	150	—	ns
CE1 Active Time	t _{CA1}	120	—	ns
CE2 Active Time	t _{CA2}	120	—	ns
OE Active Time	t _{RP}	120	—	ns
Precharge Time	t _{PC}	20	—	ns
Address Setup Time	t _{AS}	0	—	ns
Address Hold Time	t _{AH}	50	—	ns
OE Setup Time	t _{ES}	0	—	ns
Output Hold Time	t _{OH}	0	—	ns
Output Set Time	t _{LZ}	30	—	ns
CE1 Access Time	t _{CE1}	—	120	ns
CE2 Access Time	t _{CE2}	—	120	ns
OE Access Time	t _{OE}	—	120	ns
Output Floating Time	t _{OHZ}	—	20	ns

(2) Write Cycle

Parameter	Symbol	Value		Unit
		Min	Max	
Write Cycle Time	t _{WC}	150	—	ns
CE1 Active Time	t _{CA1}	120	—	ns
CE2 Active Time	t _{CA2}	120	—	ns
Precharge Time	t _{PC}	20	—	ns
Address Setup Time	t _{AS}	0	—	ns
Address Hold Time	t _{AH}	50	—	ns
Write Pulse Width	t _{WP}	120	—	ns
Data Setup Time	t _{DS}	0	—	ns
Data Hold Time	t _{DH}	50	—	ns
Write Setup Time	t _{WS}	0	—	ns

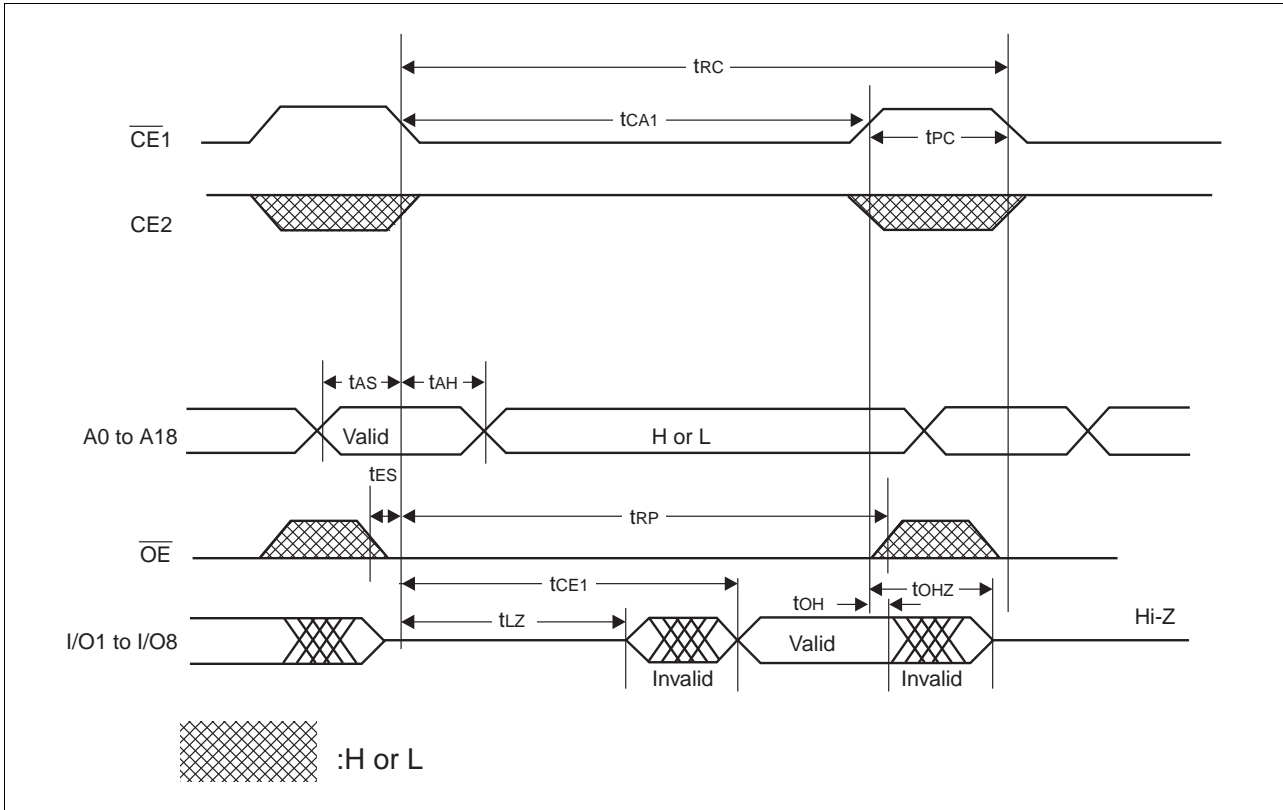
3. Pin Capacitance

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Input Capacitance	C_{IN}	$V_{DD} = V_{IN} = V_{OUT} = 0\text{ V}$, $f = 1\text{ MHz}$, $T_A = +25\text{ °C}$	—	—	10	pF
Output Capacitance	C_{OUT}		—	—	10	pF
DNU Pin Input Capacitance	C_{DNU}		—	—	10	pF

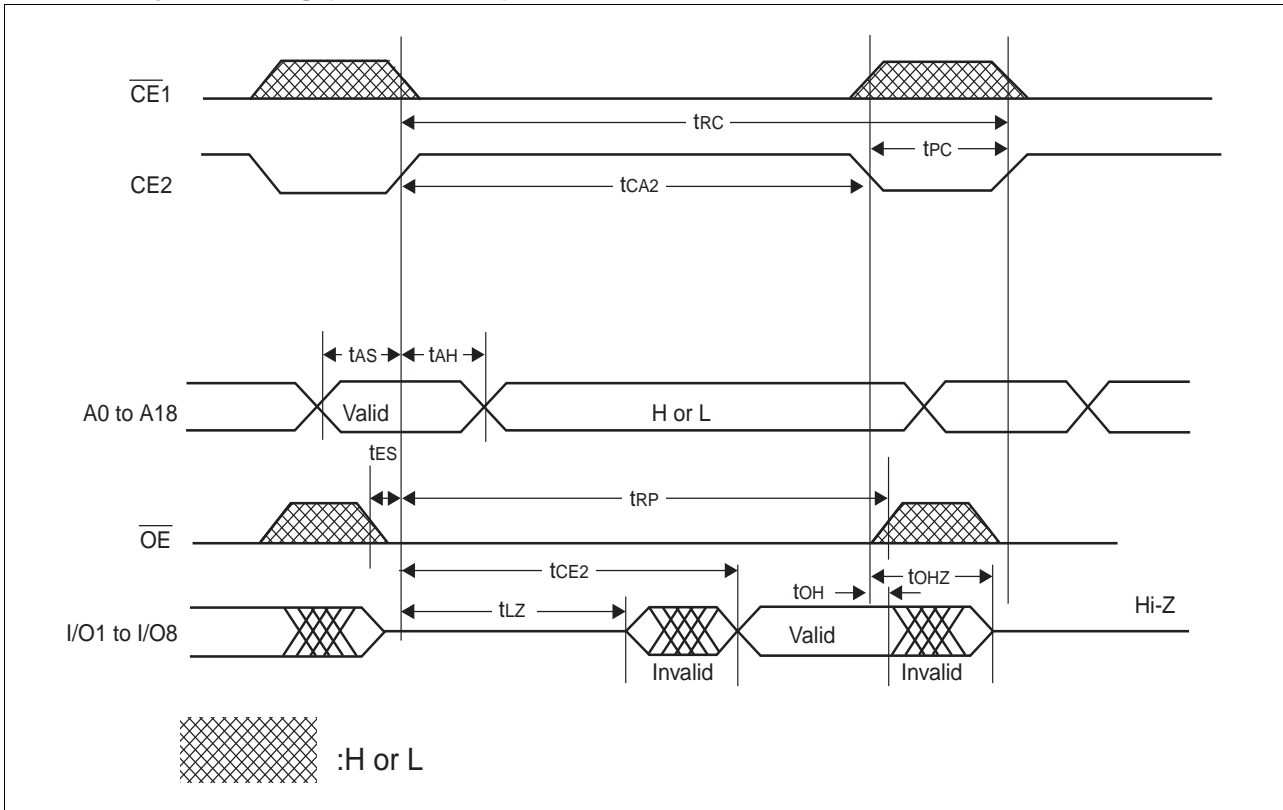
MB85R4001A

■ TIMING DIAGRAMS

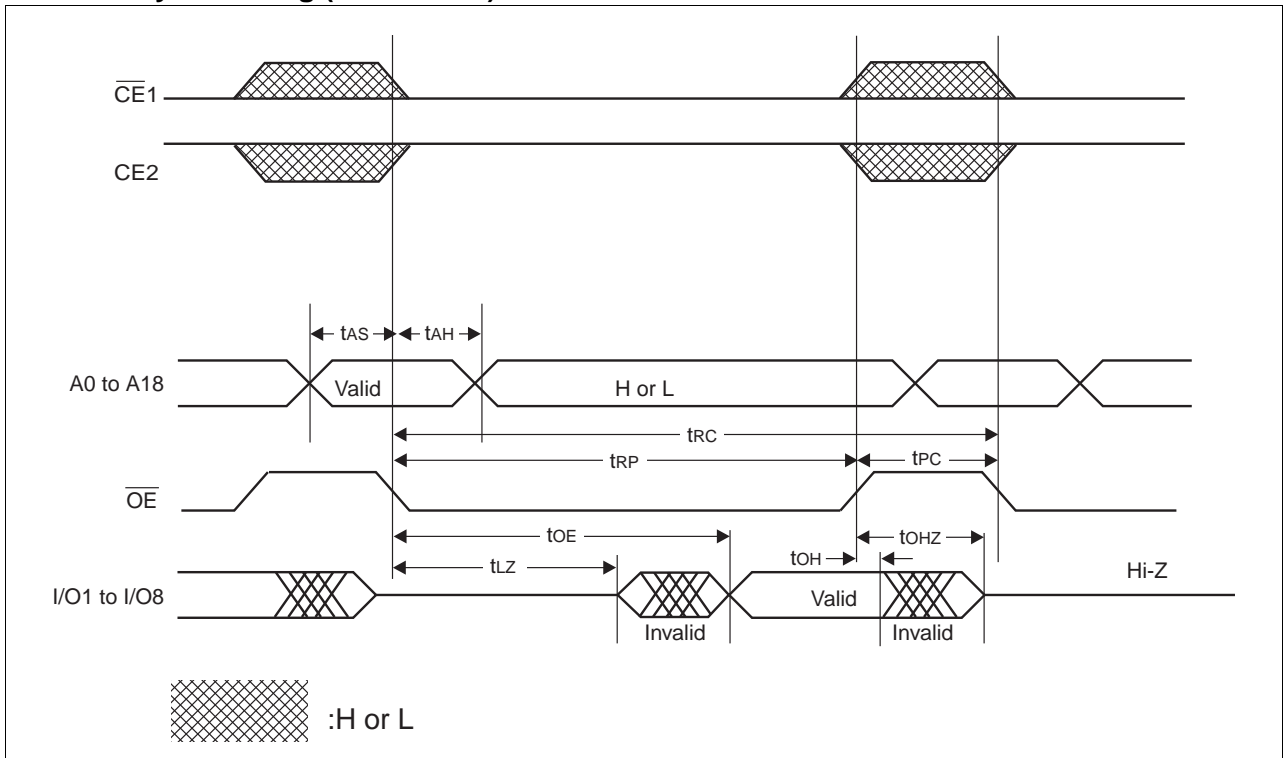
1. Read Cycle Timing ($\overline{CE1}$ Control)



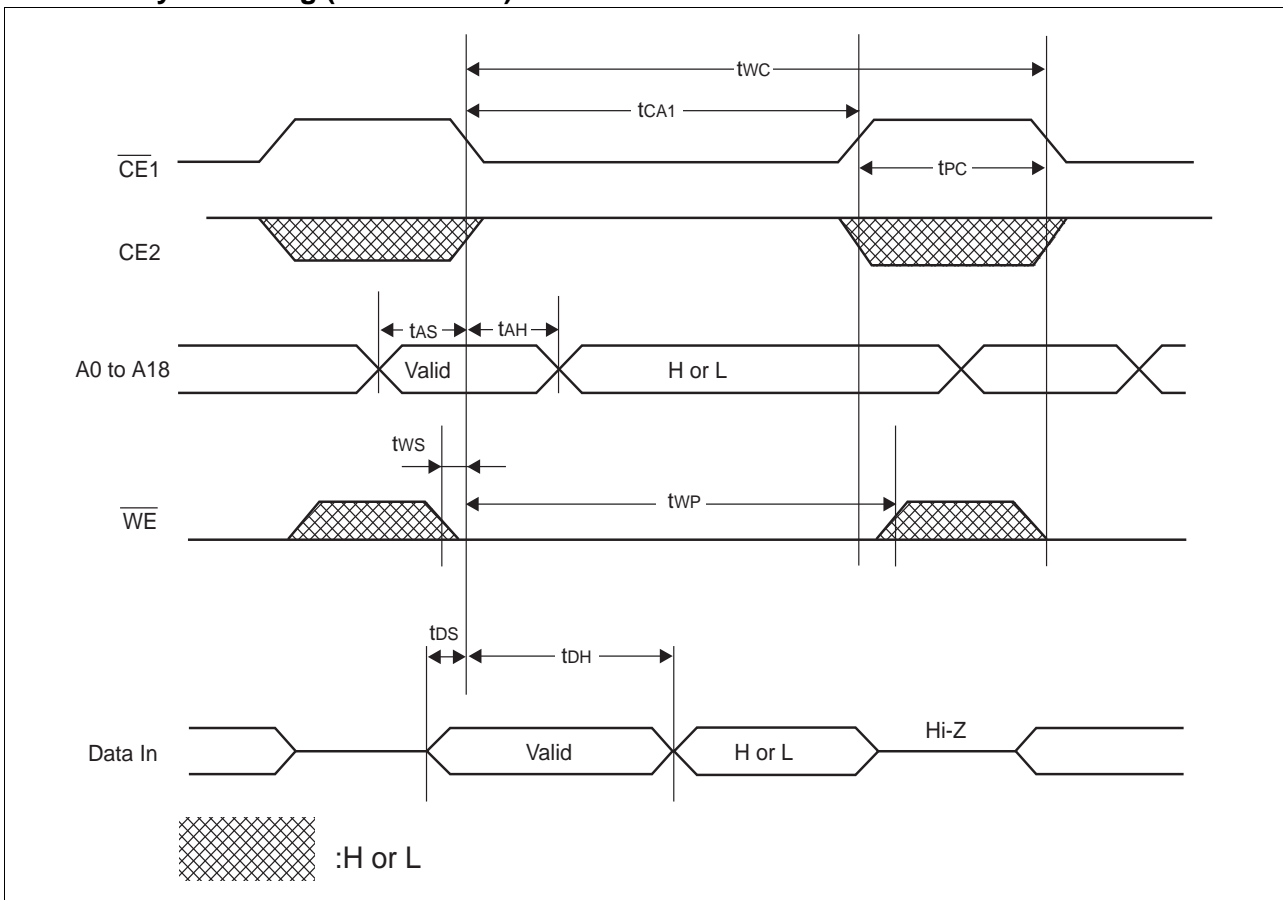
2. Read Cycle Timing (CE2 Control)



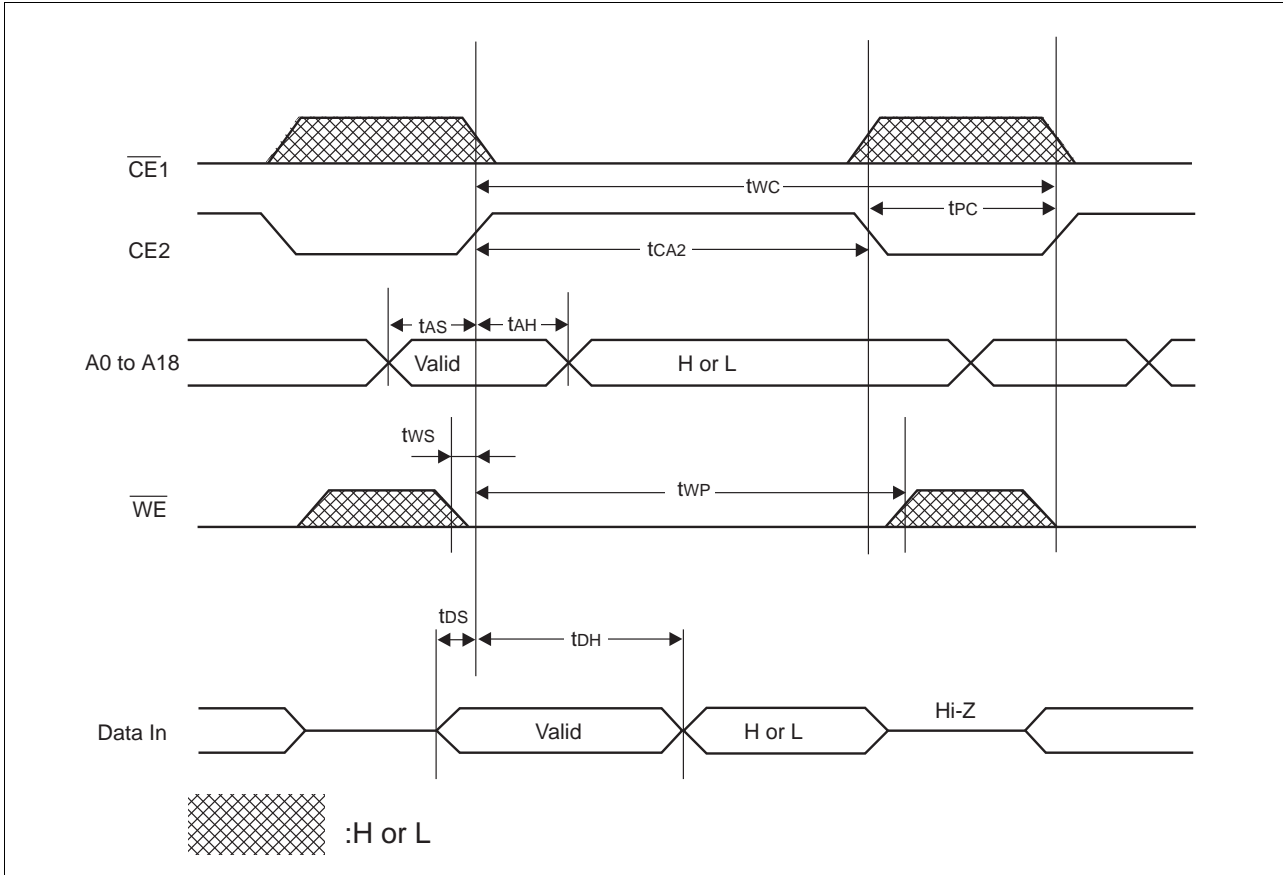
3. Read Cycle Timing (\overline{OE} Control)



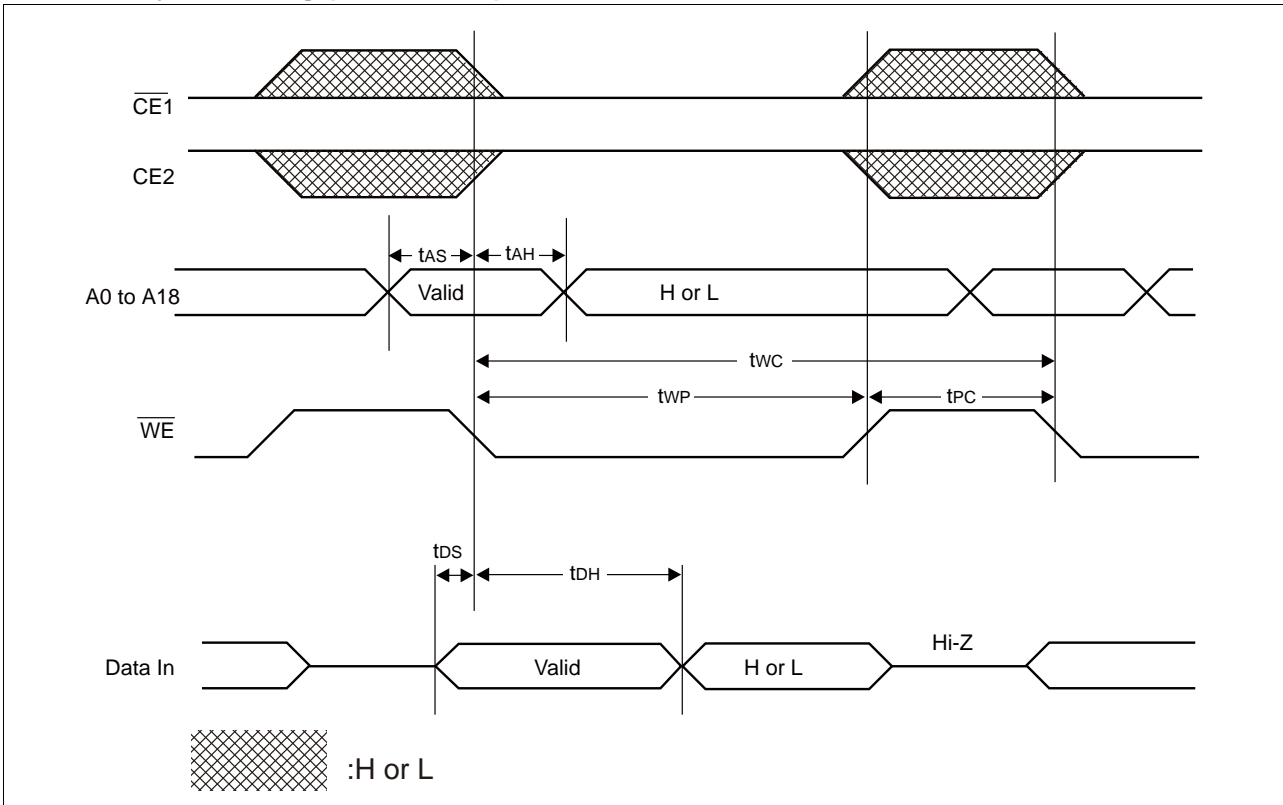
4. Write Cycle Timing ($\overline{CE1}$ Control)



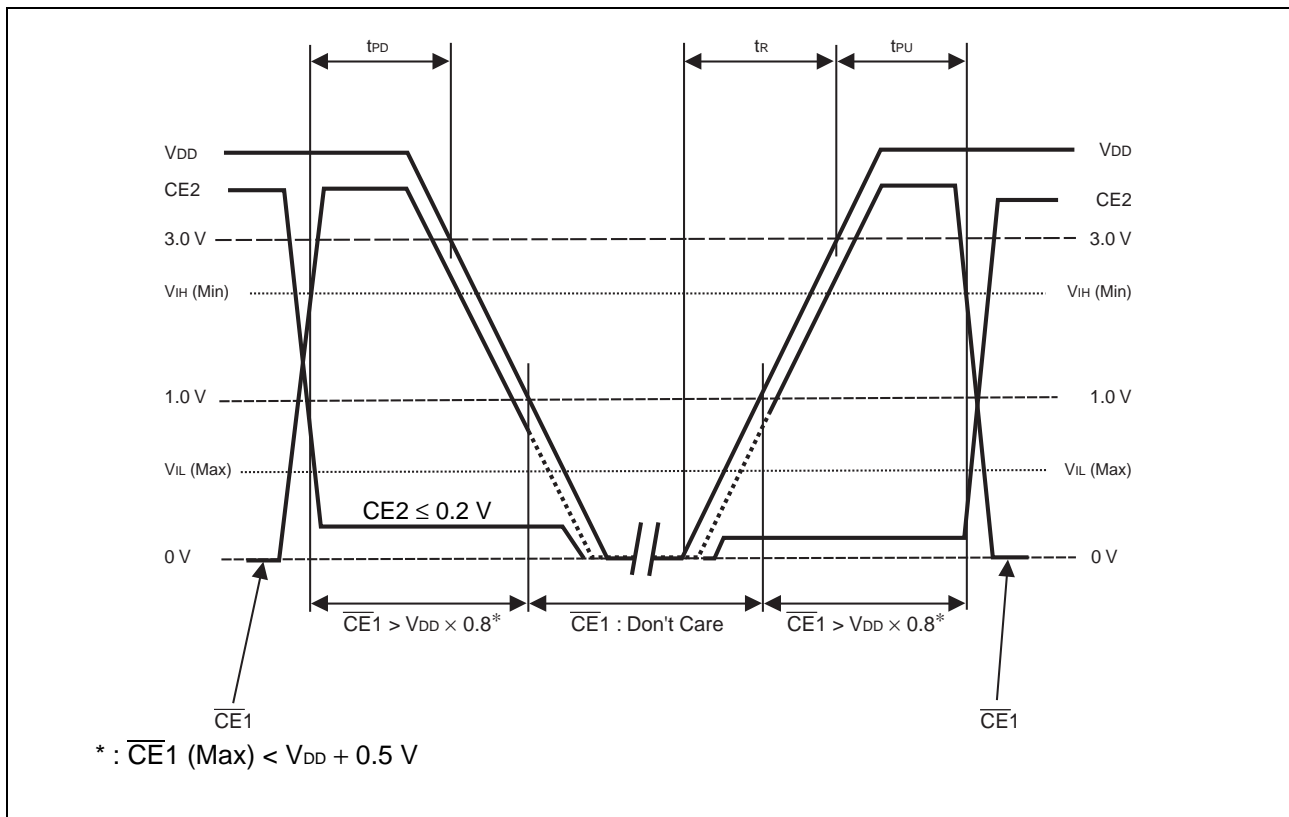
5. Write Cycle Timing (CE2 Control)



6. Write Cycle Timing (WE Control)



POWER ON/OFF SEQUENCE



Parameter	Symbol	Value			Unit
		Min	Typ	Max	
$\overline{CE1}$ level hold time for Power OFF	t_{PD}	85	—	—	ns
$\overline{CE1}$ level hold time for Power ON	t_{PU}	85	—	—	ns
Power supply rising time	t_R	0.05	—	200	ms

If the device does not operate within the specified conditions of read cycle, write cycle or power on/off sequence, memory data can not be guaranteed.

In case the power is turned on or off, use the power supply reset IC and fix the CE2 to low level, to prevent unexpected writing. Use either of $\overline{CE1}$ or CE2, or both to disable control of the device.

FRAM CHARACTERISTICS

Item	Min	Max	Unit	Parameter
Read/Write Endurance*1	10^{10}	—	Times/byte	Operation Ambient Temperature $T_A = +85 \text{ }^\circ\text{C}$
Data Retention*2	10	—	Years	Operation Ambient Temperature $T_A = +55 \text{ }^\circ\text{C}$
	55	—		Operation Ambient Temperature $T_A = +35 \text{ }^\circ\text{C}$

*1 : Total number of reading and writing defines the minimum value of endurance, as an FRAM memory operates with destructive readout mechanism.

*2 : Minimum values define retention time of the first reading/writing data right after shipment, and these values are calculated by qualification results.

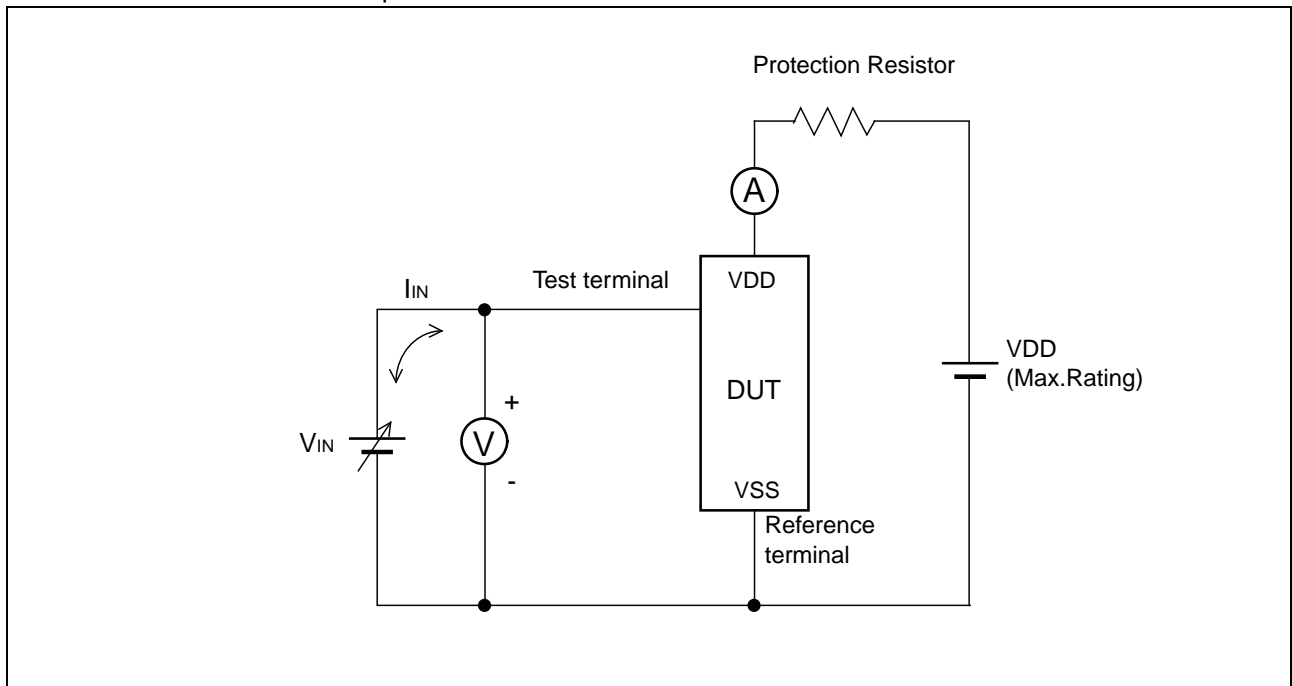
NOTES ON USE

Data written before performing IR reflow is not guaranteed after IR reflow.

■ ESD AND LATCH-UP

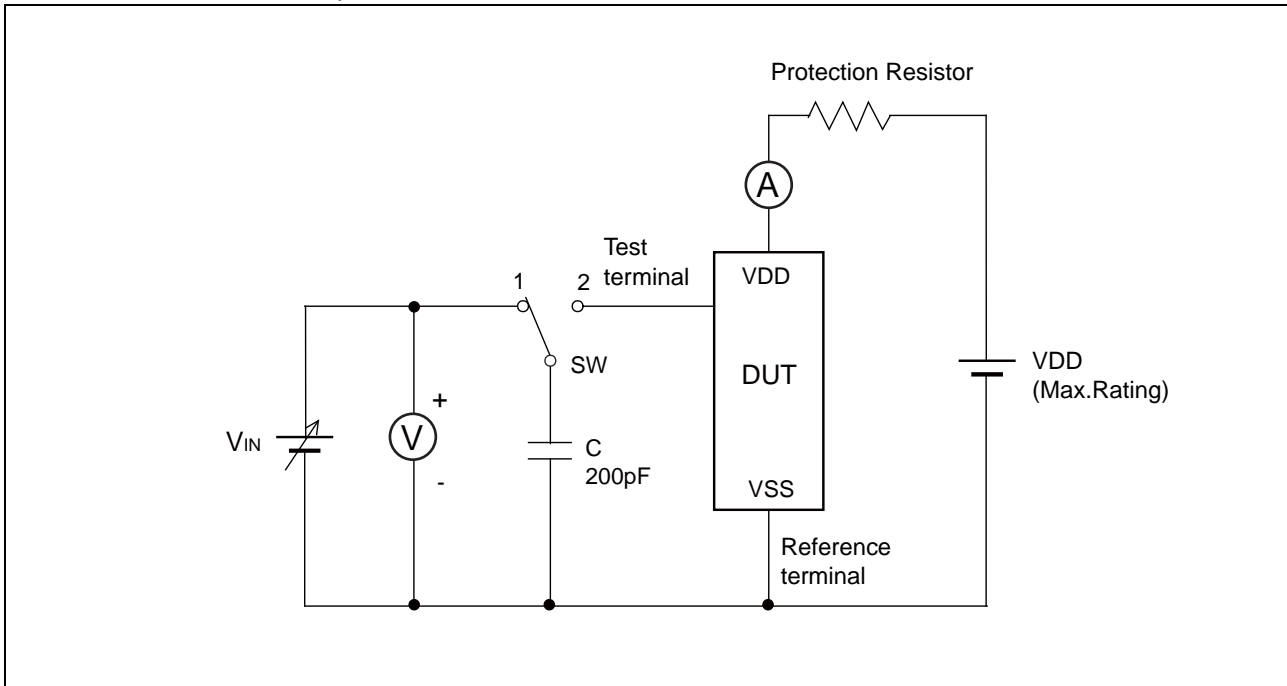
Test	DUT	Value
ESD HBM (Human Body Model) JESD22-A114 compliant	MB85R4001ANC-GE1	$\geq 2000 \text{ V} $
ESD MM (Machine Model) JESD22-A115 compliant		$\geq 200 \text{ V} $
ESD CDM (Charged Device Model) JESD22-C101 compliant		—
Latch-Up (I-test) JESD78 compliant		—
Latch-Up (V_{supply} overvoltage test) JESD78 compliant		—
Latch-Up (Current Method) Proprietary method		$\geq 300 \text{ mA} $
Latch-Up (C-V Method) Proprietary method		—

- Current method of Latch-Up Resistance Test



Note : The voltage V_{IN} is increased gradually and the current I_{IN} of 300 mA at maximum shall flow.
 Confirm the latch up does not occur under $I_{IN} = \pm 300 \text{ mA}$.
 In case the specific requirement is specified for I/O and I_{IN} cannot be 300 mA, the voltage shall be increased to the level that meets the specific requirement.

- C-V method of Latch-Up Resistance Test



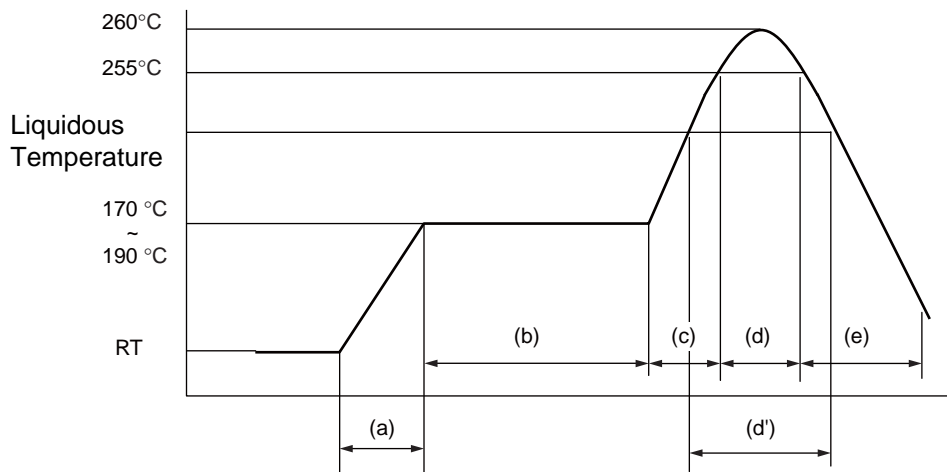
Note : Charge voltage alternately switching 1 and 2 approximately 2 sec interval. This switching process is considered as one cycle.
Repeat this process 5 times. However, if the latch-up condition occurs before completing 5 times, this test must be stopped immediately.

MB85R4001A

REFLOW CONDITIONS AND FLOOR LIFE

Item	Condition	
Method	IR (infrared reflow) , Convection	
Times	2	
Floor life	Before unpacking	Please use within 2 years after production.
	From unpacking to 2nd reflow	Within 8 days
	In case over period of floor life	Baking with 125 °C+/-3 °C for 24hrs+2hrs-0hrs is required. Then please use within 8 days. (Please remember baking is up to 2 times)
Floor life condition	Between 5 °C and 30 °C and also below 70%RH required. (It is preferred lower humidity in the required temp range.)	

Reflow Profile



- (a) Average ramp-up rate : 1 °C/s to 4 °C/s
- (b) Preheat & Soak : 170 °C to 190 °C, 60 s to 180 s
- (c) Average ramp-up rate : 1 °C/s to 4 °C/s
- (d) Peak temperature : Temperature 260 °C Max; 255 °C within 10 s
- (d') Liquidous temperature : Up to 230 °C within 40 s or
Up to 225 °C within 60 s or
Up to 220 °C within 80 s
- (e) Cooling : Natural cooling or forced cooling

Note : Temperature on the top of the package body is measured.

■ RESTRICTED SUBSTANCES

This product complies with the regulations below (Based on current knowledge as of November 2011).

- EU RoHS Directive (2002/95/EC)
- China RoHS (Administration on the Control of Pollution Caused by Electronic Information Products
(电子信息产品污染控制管理办法))
- Vietnam RoHS (30/2011/TT-BCT)

Restricted substances in each regulation are as follows.

Substances	Threshold	Contain status*
Lead and its compounds	1,000 ppm	○
Mercury and its compounds	1,000 ppm	○
Cadmium and its compounds	100 ppm	○
Hexavalent chromium compound	1,000 ppm	○
Polybrominated biphenyls (PBB)	1,000 ppm	○
Polybrominated diphenyl ethers (PBDE)	1,000 ppm	○

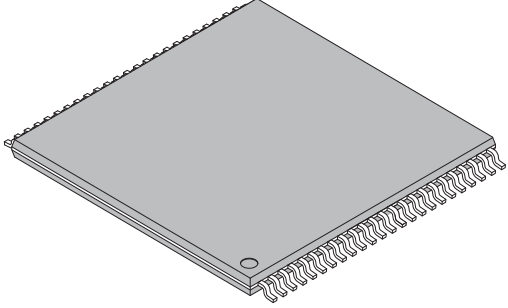
* : The mark of "○" shows below a threshold value.

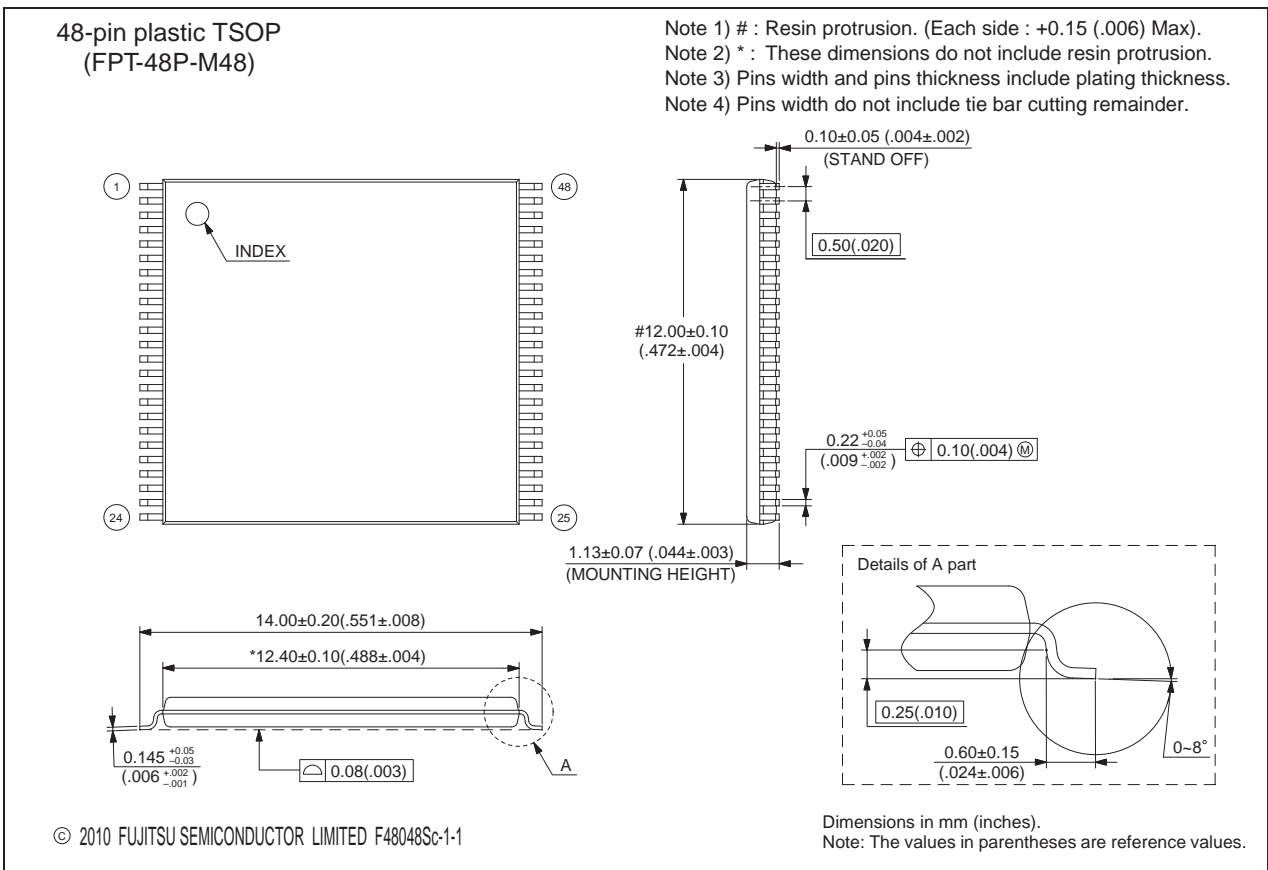
MB85R4001A

■ ORDERING INFORMATION

Part Number	Package	Shipping form	Minimum shipping quantity
MB85R4001ANC-GE1	48-pin plastic TSOP (FPT-48P-M48)	Tray	1

■ PACKAGE DIMENSIONS

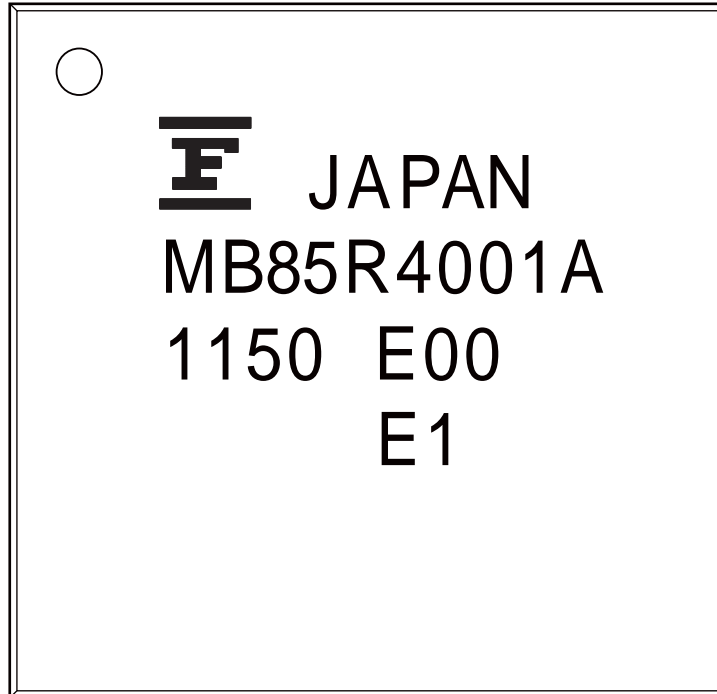
<p style="text-align: center;">48-pin plastic TSOP</p>  <p style="text-align: center;">(FPT-48P-M48)</p>	Lead pitch	0.50 mm
	Package width × package length	12.00 mm × 12.40 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.20 mm MAX
	Weight	0.36 g



MB85R4001A

■ MARKING

[MB85R4001ANC-GE1]

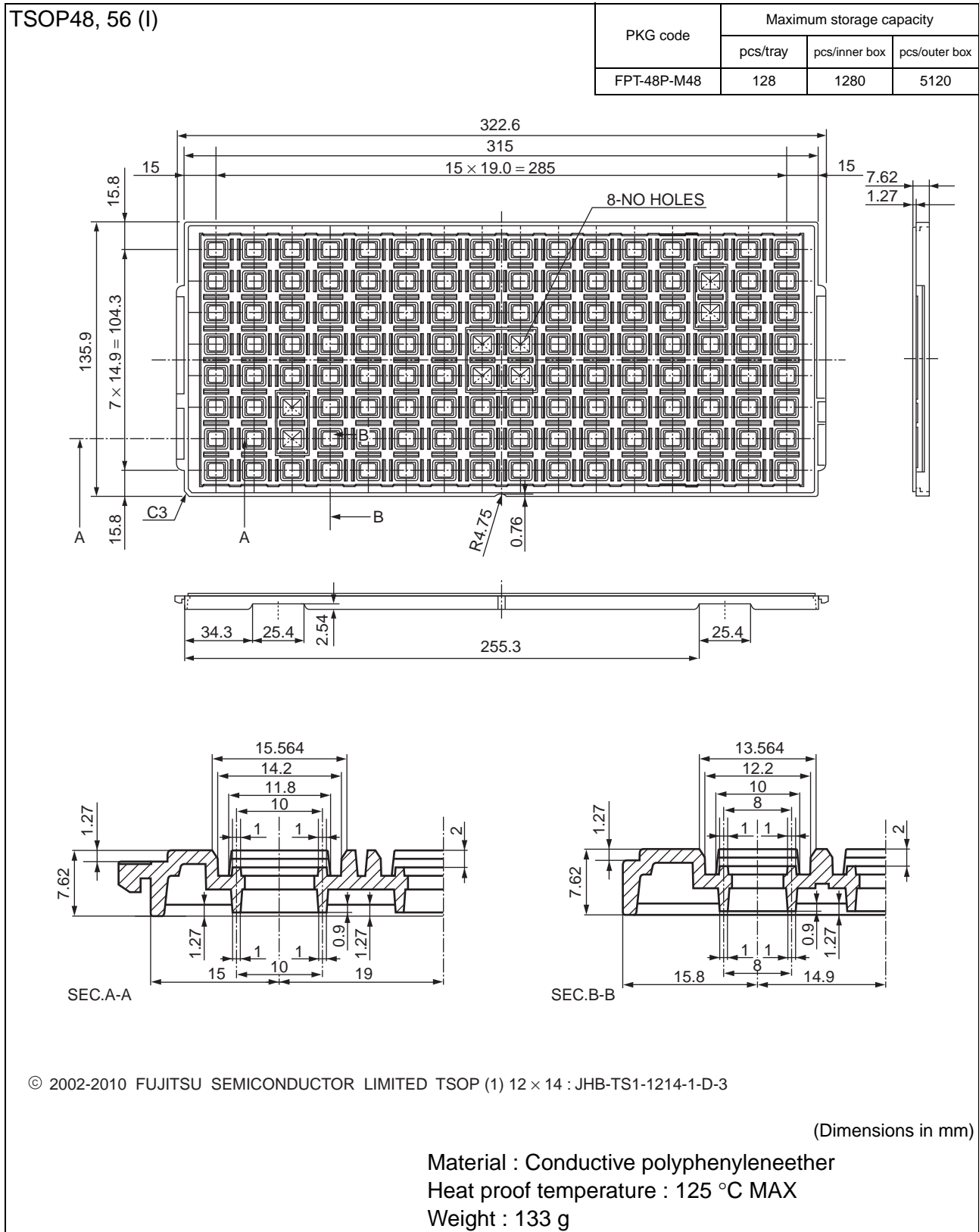


[FPT-48P-M48]

SHIPPING FORM

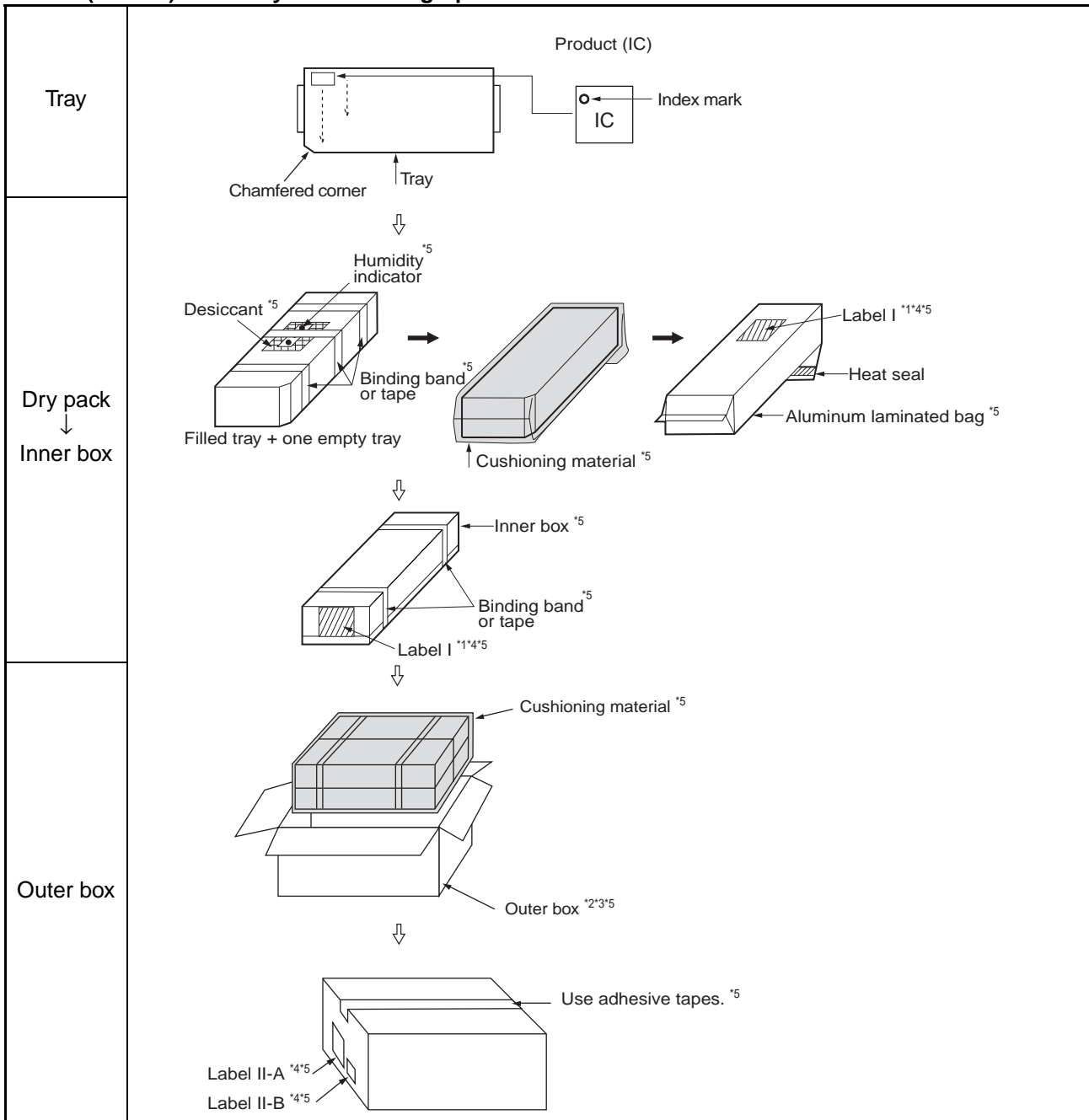
1. Tray

1.1 Tray Dimensions



MB85R4001A

1.2 IEC (JEDEC) TRAY Dry Pack Packing Specifications



*1: For a product of which part number is suffixed with "E1", a "G" (Pb) mark is displayed to the moisture barrier bag and the inner boxes.

*2: The size of the outer box may be changed depending on the quantity of inner boxes.

*3: The space in the outer box will be filled with empty inner boxes, or cushions, etc.





*4: Please refer to an attached sheet about the indication label.

*5: The packing materials except tray may differ slightly from the color and dimensions depending on country of manufacture.




Note: The packing specifications may not be applied when the product is delivered via a distributor.

1.3 Product label indicators

Label I: Label on Inner box/Moisture Barrier Bag/ (It sticks it on the reel for the emboss tapping) [C-3 Label (50mm x 100mm) Supplemental Label (20mm x 100mm)]

XXXXXXXXXXXXXXXXXX (Customer part number or FJ part number)		← C-3 Label
(3N)1 XXXXXXXXXXXXXXXXXXXX XXX	(LEAD FREE mark)	
	(Part number and quantity)	
QC PASS		
(3N)2 XXXXXXXXXXXX XXXXXX	(FJ control number)	
	(FJ control number)	
XXX pcs (Quantity)	(Customer part number or FJ part number)	
	(Customer part number or FJ part number bar code)	
XXXX/XX/XX (Packed years/month/day)	ASSEMBLED IN xxxx	← Perforated line
XXXXXXXXXXXXXXXXXX (Customer part number or FJ part number)		← Supplemental Label
(FJ control number bar code)		
	XX/XX (Package count)	
XXXXXXXXXXXX (FJ control number)	(Lot Number and quantity)	
XXXXXXXXXXXXXXXXXX (Comment)		

Label II-A: Label on Outer box [D Label] (100mm x 100mm)

発注者 XXXXXXXXXXXXXXXX (Customer Name) (CUST.)		受注者 (VENDOR) 富士通		← D Label
受渡場所名 XXXXXXXXXXXX (Delivery Address) (DELIVERY POINT)		セミコンダクター株式会社		
納品キー番号 XXXXXXXXXXXXXXXX (TRANS.NO.) (FJ control number)		XXX (FJ control number)		
品名コード XXXXXXXXXXXXXXXX (PART NO.) (Customer part number or FJ part number)		XXX (FJ control number)		
		XXXXXXXXXXXXXXXXXX (Part number)		
品名 (PART NAME) XXXXXXXXXXXXXXXX (Part number)				
人数/納入数量 XXX/XXX (Q'TY/TOTAL Q'TY)		単位 XX (UNIT)		
発注者用備考 (CUSTOMER'S REMARKS) XXXXXXXXXXXXXXXXXXXXX		梱包個数 (PACKAGE COUNT) XXX/XXX		
(3N)3 XXXXXXXXXXXXXXXX XXX		(FJ control number + Product quantity)		
		(FJ control number + Product quantity bar code)		
(3N)4 XXXXXXXXXXXXXXXX XXX		(Part number + Product quantity)		
		(Part number + Product quantity bar code)		
(3N)5 XXXXXXXXXXXXXXXX		(FJ control number)		
		(FJ control number bar code)		

Label II-B: Outer boxes product indicate

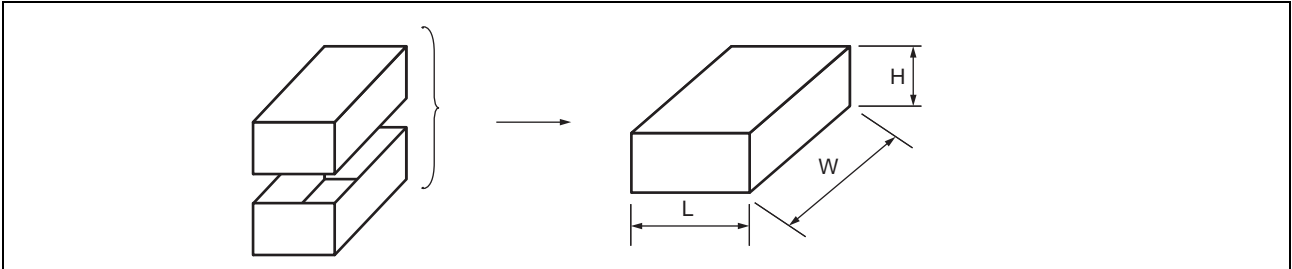
XXXXXXXXXXXXXXXXXX (Part number)		
(Lot Number)	(Count)	(Quantity)
XXXX-XXX	X 箱	XXX 個
XXXX-XXX	X 箱	XXX 個
	計	XXX 個

Note: Depending on shipment state, "Label II-A" and "Label II-B" on the external boxes might not be printed.

MB85R4001A

1.4 Dimensions for Containers

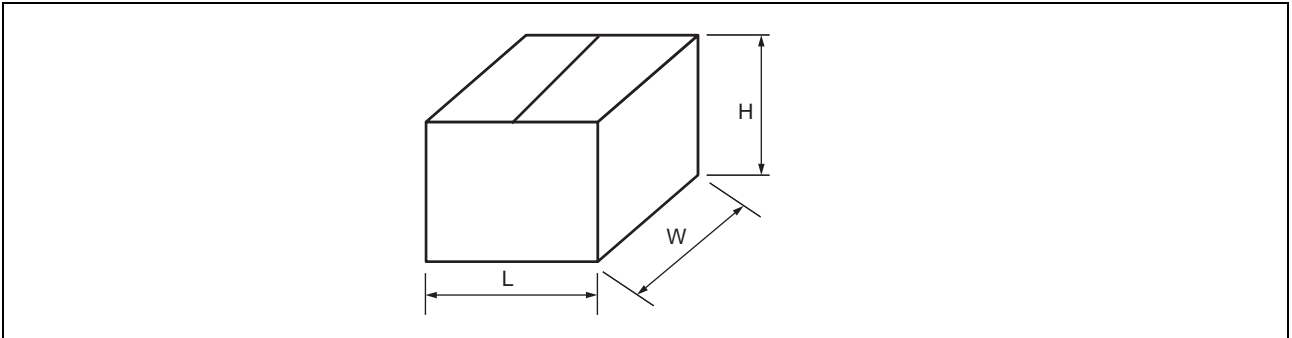
(1) Dimensions for inner box



L	W	H
165	360	75

(Dimensions in mm)

(2) Dimensions for outer box



L	W	H
355	385	195

(Dimensions in mm)

■ MAJOR CHANGES IN THIS EDITION

A change on a page is indicated by a vertical line drawn on the left side of that page.

Page	Section	Change Results
1	■ FEATURES	Revised the Data retention 10 years (+ 55 °C) →10 years (+ 55 °C), 55 years (+ 35 °C)
4	■ ABSOLUTE MAXIMUM RANGES	Revised the Storage Temperature – 40 °C → – 55 °C
11	■ POWER ON/OFF SEQUENCE	Deleted the following description: “Because turning the power-on from an intermediate level cause malfunction, when the power is turned on, V _{DD} is required to be started from 0V (see the figure below). ” Moved the following description under the table: “If the device does not operate within the specified conditions of read cycle, write cycle or power on/off sequence, memory data can not be guaranteed. In case the power is turned on or off, use the power supply reset IC and fix the CE2 to low level, to prevent unexpected writing. Use either of $\overline{CE1}$ or CE2, or both to disable control of the device.”
	■ FRAM CHARACTERISTICS	Revised the table and Note

MB85R4001A

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